

PCB Specification for SFP+ Mezzanine Card.

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Board Name: SFP+ Mezzanine Card

Board Revision: 0

Release: A

PCB Details

PCB Specifications:	IPC 6012 Class 2
Finished Board Size:	110 x 90 (mm)
PCB Type:	Multilayer
Layer Count:	8
Dielectric:	-
Nominal Board Thickness:	1.59mm – 8 layer stackup
Hole Tolerance:	-
Finish:	ENIG
Soldermask:	Green
Silkscreen:	White
Minimum clearance:	4 mil

PCB Stackup

Layer	#	Copper Thickness	Dielectric	Filename
Silkscreen Top				SFPP.GTO
Soldermask Top				SFPP.GTS
Signal Top (L1_S1)	1	17u	0.015mm	SFPP.GTL
Core			0.127mm	
Power plane 1 (L2_PGND)	2	35u		SFPP.GP1
Pre-preg			0.203mm	
Mid layer 1 (L3_S2)	3	17u	0.015mm	SFPP.G1
Core			0.203mm	
Power plane 2 (L4_P1V2)	4	35u		SFPP.GP2
Pre-preg			0.381mm	
Power plane 3 (L5_P1V8)	5	35u		SFPP.GP3
Core			0.203mm	
Mid layer 2 (L6_S3)	6	17u	0.015mm	SFPP.G2
Pre-preg			0.203mm	
Power plane 4 (L7_PGND)	7	35u		SFPP.GP4
Core			0.127mm	
Signal Bottom (L8_S4)	8	17u	0.015mm	SFPP.GBL
Soldermask Bottom				SFPP.GBS
Silkscreen Bottom				SFPP.GBO

Impedance Controlled Traces

All impedance matching to +/- 10%

Microstrip:

Layers: Signal Top (#1) and Bottom (#8)
Target Impedance: 50 ohms
Trace Thickness: 5mil (0.127mm)